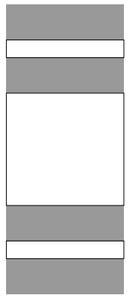
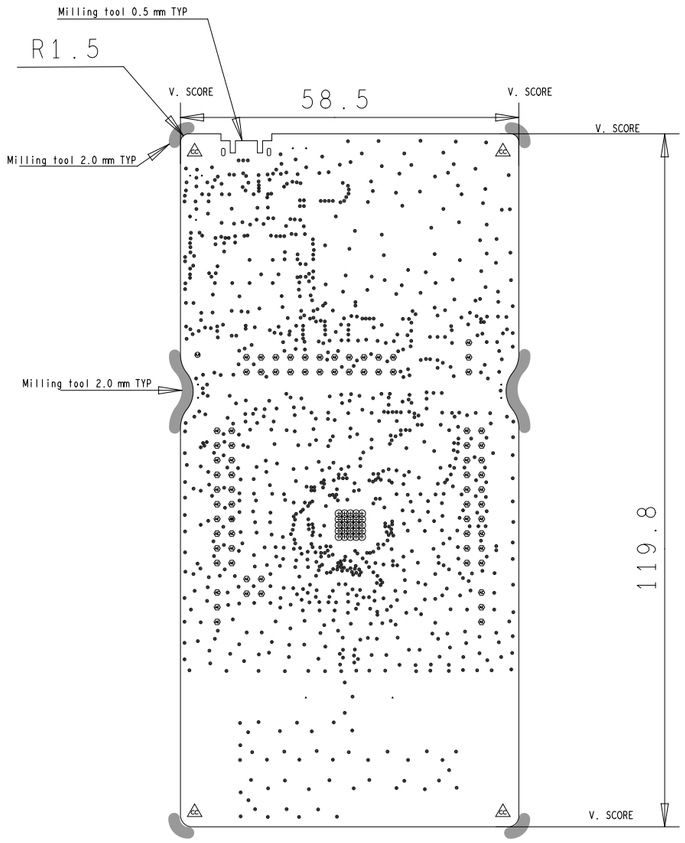
DESIGN CROSS SECTION CHART
TOTAL THICKNESS 1.6 MM AFTER PRESS



L1: TOP CONDUCTOR - COPPER + PLATING 0.035 MM
* DIELECTRIC - FR-4 0.175 MM (AFTER PRESS,TOP PRIORITY)
L2: L2 PLANE - COPPER 0.035 MM
* DIELECTRIC - FR-4 1.11 MM
L3: L3 PLANE - COPPER 0.035 MM
* DIELECTRIC - FR-4 0.175 MM
L4: BOTTOM CONDUCTOR - COPPER + PLATING 0.035 MM



DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILLIMETERS				
FIGURE	FINISHED_SIZE	ROTATION	PLATED	QTY
•	0.2	-	PLATED	1049
⊕	0.201	-	PLATED	25
⊗	1.05	-	PLATED	75
⊜	1.1	-	PLATED	1
◬	3.2	-	PLATED	4
·	0.899	-	NON-PLATED	6
·	1.0	-	NON-PLATED	3
·	3.2	-	NON-PLATED	2
▯	1.3x0.6	90.000	PLATED	2

DESIGN INFORMATION

MIN. TRACK WIDTH: 0.15 mm
MIN. CLEARANCE: 0.15 mm
MIN. VIA PAD SIZE: 0.40 mm
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/-150 um, HOLES +/-80 um
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/-80 um

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER _____
THICKNESS: [X] 1.6mm +/-10% [ ] OTHER _____
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____

DRILLING:
REFERENCE: [ ] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER _____

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SILKSCREEN RESIST COLOR: [ ] GREEN [X] OTHER RED
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS —> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-VO REQUIREMENTS.
PCB MUST BEAR THE UL94V-O UL REG. MATERIAL ID NUMBER: BOTTOM LAYER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [X] NONE [ ] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL VIAS REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

TITLE: LP-CC1311P3
PROJECT NUMBER: MCU084
FILE NAME: LP-CC1311P3.brd

DESIGNER:	DATE:	REVISION:
RGW	2021-11-01	A
SCALE: 1.00	ALLEGRO DESIGNER VERSION: 17.2	

TEXAS INSTRUMENTS	
DRILL	LP-CC1311P3 MCU084 Rev. A
DATE: 2021-11-01	